

WHAT IS CLAIMED IS:

1. A microsystem package structure, comprising:

a first substrate;

5 a chip disposed on the first substrate and electrically connected to the first substrate;

an adhesive structure disposed on the chip, wherein the adhesive structure has at least an opening and is in an annular shape;

a carrying substrate disposed on the adhesive structure, wherein an interspace is formed between the chip, the adhesive structure and the carrying substrate;

10 a micro-mechanism disposed on the carrying substrate;

an annular body attached to the first substrate, wherein a chamber is formed between the annular body and the first substrate and wherein the chip, the carrying substrate, the micro-mechanism and the adhesive structure are disposed within the chamber; and

15 a second substrate disposed on the annular body and sealed the chamber, wherein a pressure of the interspace is balanced with that of the chamber.

2. The microsystem package structure of claim 1, wherein a first surface of the chip comprises a memory region and a plurality of chip nodes are arranged along a peripheral region of the memory region on the first surface of the chip, and wherein the
20 adhesive structure is disposed between the memory region and the chip nodes on the first surface of the chip.

3. The microsystem package structure of claim 1, wherein the micro-mechanism includes a micro-mirror mechanism and the micro-mirror mechanism includes a plurality of micro-mirror sets, each micro-mirror set comprising:

a supporting stalk, wherein one end of the stalk is connected to the carrying substrate;

a hinge, wherein the other end of the stalk is connected to the hinge; and

a micromirror, wherein one side of the micromirror is connected to the hinge, so
5 that the micromirror rotates by using the hinge as a rotation center.

4. The microsystem package structure of claim 1, wherein the microsystem package structure further comprises a plurality of wires, for electrically connecting the chip and the first substrate.

5. The microsystem package structure of claim 1, wherein the annular body and
10 the first substrate are fabricated integrally.

6. The microsystem package structure of claim 1, wherein the microsystem package structure further comprises a desiccant in the closed chamber between the annular body, the second substrate and the first substrate.

7. The microsystem package structure of claim 1, wherein the second substrate is
15 made of glass.

8. The microsystem package structure of claim 1, wherein the annular adhesive structure is tetragonal.

9. The microsystem package structure of claim 8, wherein the opening is disposed in a middle portion of a side of the adhesive structure.

20 10. The microsystem package structure of claim 8, wherein the opening is disposed at a corner of the adhesive structure.

11. The microsystem package structure of claim 8, wherein the adhesive structure has a plurality of openings at corners of the adhesive structure.

12. The microsystem package structure of claim 1, wherein the adhesive structure further includes a protrusion around the opening and on an outer side of the adhesive structure.

13. The microsystem package structure of claim 1, wherein the carrying
5 substrate and the first substrate are transparent.

14. The microsystem package structure of claim 1, wherein the chip is a memory chip.